



## Initial Product/Process Change Notification

Document #: IPCN23822X

Issue Date: 09 Feb 2021

<b>Title of Change:</b>	Transfer below parts from FCI to ASE CL (bump) and Tarlac (FT/singulation/TnR) N24S128C4DYT3G N24S64C4DYT3G N34TS108C6ECT5G	
<b>Proposed First Ship date:</b>	30 Sep 2021 or earlier if approved by customer	
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Doina.Patrascu@onsemi.com">Doina.Patrascu@onsemi.com</a>	
<b>PCN Samples Contact:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:PCN.samples@onsemi.com">&lt;PCN.samples@onsemi.com&gt;</a> . Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <a href="mailto:PCN.Support@onsemi.com">&lt;PCN.Support@onsemi.com&gt;</a>	
<b>Marking of Parts/ Traceability of Change:</b>	Traceability of change will be on the date code	
<b>Change Category:</b>	Test Change, Assembly Change	
<b>Change Sub-Category(s):</b>	Manufacturing Site Transfer	
<b>Sites Affected:</b>		
<b>ON Semiconductor Sites</b>	<b>External Foundry/Subcon Sites</b>	
ON Semiconductor Tarlac, Philippines	ASECL, Taiwan (ChungLi)	
	Flipchip International, USA	
<b>Description and Purpose:</b>		
There are no product material changes as a result of this change.		
	<b>Before Change Description</b>	<b>After Change Description</b>
Bump Location Change	Flipchip International-USA	ASE CL (ASE CHUNGLI), Taiwan
Laser Marking Location Change	Flipchip International-USA	OSPI Tarlac, Philippines
<b>Reason for Change:</b> Transfer to new manufacturing location, to support short and long term demand.		
<b>Marking:</b> There is no product marking change as a result of this change. Traceability of change will be on the date code		

**Qualification Plan:**

QV DEVICE NAME: N24C256C6DYT3G

PACKAGE: WLCSP 6

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=150°C, 1.2*Vcc_max	1008 hrs
ELFR	JESD22-A108	Ta=150°C, 1.2*Vcc_max	48hrs
HTSL	JESD22-A103	Ta=150°C	1008hrs
TC	JESD22-A104	Ta = -40°C to +125°C	850 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	5x reflow

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PACKAGE: WLCSP 6

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ELFR	JESD22-A108	Ta=150°C, 1.2*Vcc_max	48hrs
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TC	JESD22-A104	Ta = -40°C to +125°C	850 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	5x reflow

Estimated date for qualification completion: 30 Sep 2021

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [\*\*PCN Customized Portal\*\*](#).

Part Number	Qualification Vehicle
N24S128C4DYT3G	N24S128C4DYT3G
N24S64C4DYT3G	N24S128C4DYT3G
N34TS108C6ECT5G	N34TS108C6ECT5G